

TrenchT2™ HiperFET N-Channel Power MOSFET

FMM150-0075X2F

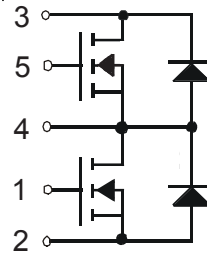
$$V_{DSS} = 75V$$

$$I_{D25} = 120A$$

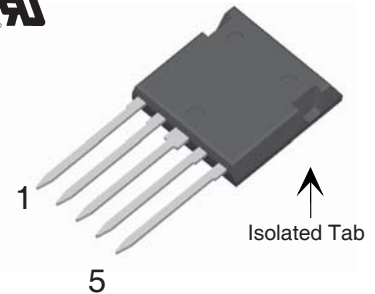
$$R_{DS(on)} \leq 5.8m\Omega$$

$$t_{rr(typ)} = 66ns$$

Phase Leg Topology



ISOPLUS i4-Pak™



| Symbol | Test Conditions | Maximum Ratings | |
|------------|--------------------------------------|-------------------|-------|
| T_J | | -55 ... +175 | °C |
| T_{JM} | | 175 | °C |
| T_{stg} | | -55 ... +175 | °C |
| V_{ISOL} | 50/60Hz, RMS, t = 1min, Leads-to-Tab | 2500 | ~V |
| T_L | 1.6mm (0.062 in.) from Case for 10s | 300 | °C |
| T_{SOLD} | Plastic Body for 10s | 260 | °C |
| F_C | Mounting Force | 20..120 / 4.5..27 | N/lb. |

| Symbol | Test Conditions | Maximum Ratings | |
|-----------|--|-----------------|------|
| V_{DSS} | $T_J = 25^\circ C$ to $175^\circ C$ | 75 | V |
| V_{DGR} | $T_J = 25^\circ C$ to $175^\circ C$, $R_{GS} = 1M\Omega$ | 75 | V |
| V_{GSM} | Transient | ± 30 | V |
| I_{D25} | $T_C = 25^\circ C$ | 120 | A |
| I_{DM} | $T_C = 25^\circ C$, Pulse Width Limited by T_{JM} | 500 | A |
| I_A | $T_C = 25^\circ C$ | 115 | A |
| E_{AS} | $T_C = 25^\circ C$ | 850 | mJ |
| dV/dt | $I_S \leq I_{DM}$, $V_{DD} \leq V_{DSS}$, $T_J \leq 175^\circ C$ | 20 | V/ns |
| P_D | $T_C = 25^\circ C$ | 170 | W |

Features

- Silicon Chip on Direct-Copper Bond (DCB) Substrate
 - UL Recognized Package
 - Isolated Mounting Surface
 - 2500V Electrical Isolation
- Avalanche Rated
- Low Q_G
- Low Drain-to-Tab Capacitance
- Low Package Inductance

Advantages

- Easy to Mount
- Space Savings
- High Power Density

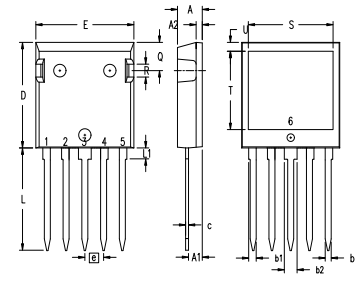
Applications

- DC-DC Converters
- Battery Chargers
- Switched-Mode and Resonant-Mode Power Supplies
- DC Choppers
- AC Motor Drives
- Uninterruptible Power Supplies
- High Speed Power Switching Applications

| Symbol | Test Conditions | Characteristic Values | | |
|---------------|--|-----------------------|------|------|
| | | Min. | Typ. | Max. |
| C_p | Coupling Capacitance Between Shorted Pins and Mounting Tab in the Case | | 40 | pF |
| d_S, d_A | Pin - Pin | 1.7 | | mm |
| d_S, d_A | Pin - Backside Metal | 5.5 | | mm |
| Weight | | | 9 | g |

| Symbol | Test Conditions | Characteristic Values | | |
|--------------|--|-----------------------|------|---------------------------|
| | | Min. | Typ. | Max. |
| BV_{DSS} | $V_{GS} = 0V, I_D = 250\mu A$ | 75 | | V |
| $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\mu A$ | 2.0 | | 4.0 V |
| I_{GSS} | $V_{GS} = \pm 20V, V_{DS} = 0V$ | | | ± 200 nA |
| I_{DSS} | $V_{DS} = V_{DSS}, V_{GS} = 0V$ | | | 25 μA 250 μA |
| | $T_J = 150^\circ C$ | | | |
| $R_{DS(on)}$ | $V_{GS} = 10V, I_D = 100A, \text{Note 1}$ | | | 5.8 m Ω |
| g_{fs} | $V_{DS} = 10V, I_D = 60A, \text{Note 1}$ | 50 | 83 | S |
| C_{iss} | $V_{GS} = 0V, V_{DS} = 25V, f = 1\text{ MHz}$ | | 10.5 | nF |
| C_{oss} | | | | |
| C_{rss} | | | | |
| $t_{d(on)}$ | Resistive Switching Times $V_{GS} = 10V, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 115A$ $R_G = 2\Omega$ (External) | | 23 | ns |
| t_r | | | | |
| $t_{d(off)}$ | | | | |
| t_f | | | | |
| $Q_{g(on)}$ | $V_{GS} = 10V, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 100A$ | | 178 | nC |
| Q_{gs} | | | | |
| Q_{gd} | | | | |
| R_{thJC} | | | | 0.88 $^\circ C/W$ |
| R_{thCS} | | 0.15 | | $^\circ C/W$ |

ISOPLUS i4-Pak™ Outline



NOTE: Bottom heatsink meets 3000 Volts AC 1 sec isolation to the other pins.

| SYM | INCHES | | MILLIMETERS | |
|-----|----------|------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | .190 | .205 | 4.83 | 5.21 |
| A1 | .102 | .118 | 2.59 | 3.00 |
| A2 | .046 | .085 | 1.17 | 2.16 |
| b | .045 | .055 | 1.14 | 1.40 |
| b1 | .058 | .068 | 1.47 | 1.73 |
| b2 | .100 | .110 | 2.54 | 2.79 |
| C | .020 | .029 | 0.51 | 0.74 |
| D | .819 | .840 | 20.80 | 21.34 |
| E | .770 | .799 | 19.56 | 20.29 |
| e | .150 BSC | | 3.81 BSC | |
| L | .780 | .840 | 19.81 | 21.34 |
| L1 | .083 | .102 | 2.11 | 2.59 |
| Q | .210 | .244 | 5.33 | 6.20 |
| R | .100 | .180 | 2.54 | 4.57 |
| S | .660 | .690 | 16.76 | 17.53 |
| T | .590 | .620 | 14.99 | 15.75 |
| U | .065 | .080 | 1.65 | 2.03 |

Ref: IXYS CO 0077 R0

Source-Drain Diode

| Symbol | Test Conditions | Characteristic Values | | |
|----------|---|-----------------------|------|-------|
| | | Min. | Typ. | Max. |
| I_S | $V_{GS} = 0V$ | | | 230 A |
| I_{SM} | Repetitive, Pulse Width Limited by T_{JM} | | | 900 A |
| V_{SD} | $I_F = 75A, V_{GS} = 0V, \text{Note 1}$ | | | 1.5 V |
| t_{rr} | $I_F = 115A, -di/dt = 100A/\mu s$ $V_R = 37V, V_{GS} = 0V$ | | 66 | ns |
| I_{RM} | | | | |
| Q_{RM} | | | | |
| | | | 4.4 | A |
| | | | 145 | nC |

Note 1. Pulse test, $t \leq 300\mu s$, duty cycle, $d \leq 2\%$.

ADVANCE TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated objective result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

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| | | | | | | | | | | |
|--|-----------|-----------|-----------|-----------|--------------|--------------|--------------|--------------|--------------|-------------|
| IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: | 4,835,592 | 4,931,844 | 5,049,961 | 5,237,481 | 6,162,665 | 6,404,065 B1 | 6,683,344 | 6,727,585 | 7,005,734 B2 | 7,157,338B2 |
| | 4,850,072 | 5,017,508 | 5,063,307 | 5,381,025 | 6,259,123 B1 | 6,534,343 | 6,710,405 B2 | 6,759,692 | 7,063,975 B2 | |
| | 4,881,106 | 5,034,796 | 5,187,117 | 5,486,715 | 6,306,728 B1 | 6,583,505 | 6,710,463 | 6,771,478 B2 | 7,071,537 | |

Fig. 1. Output Characteristics
@ $T_J = 25^\circ\text{C}$

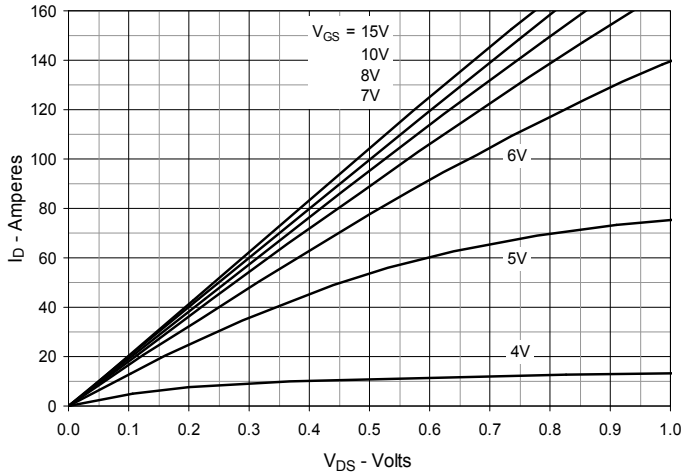


Fig. 2. Extended Output Characteristics
@ $T_J = 25^\circ\text{C}$

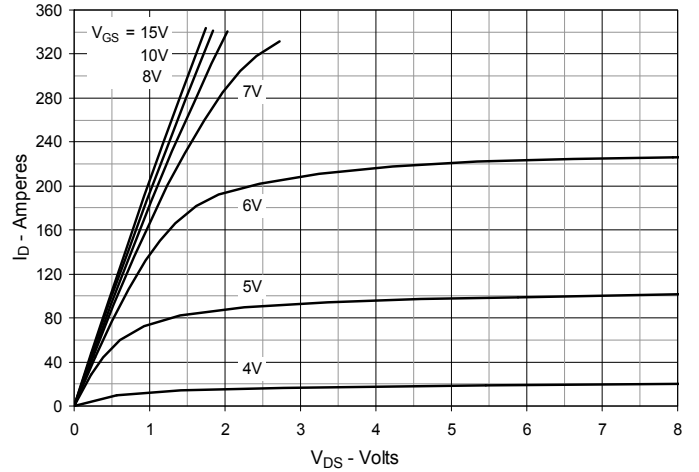


Fig. 3. Output Characteristics
@ $T_J = 150^\circ\text{C}$

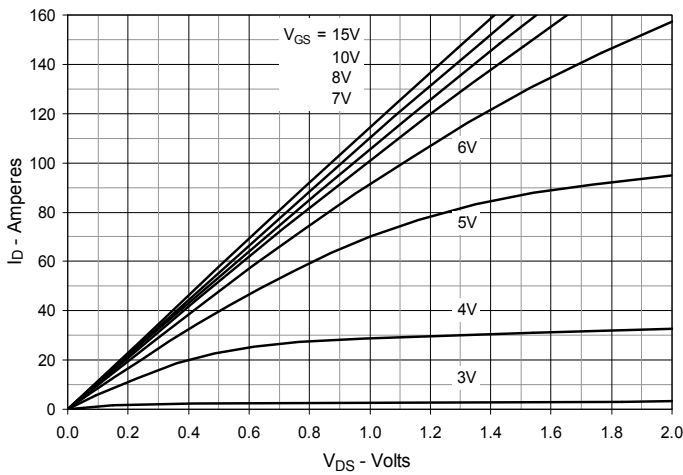


Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 75\text{A}$ Value vs. Junction Temperature

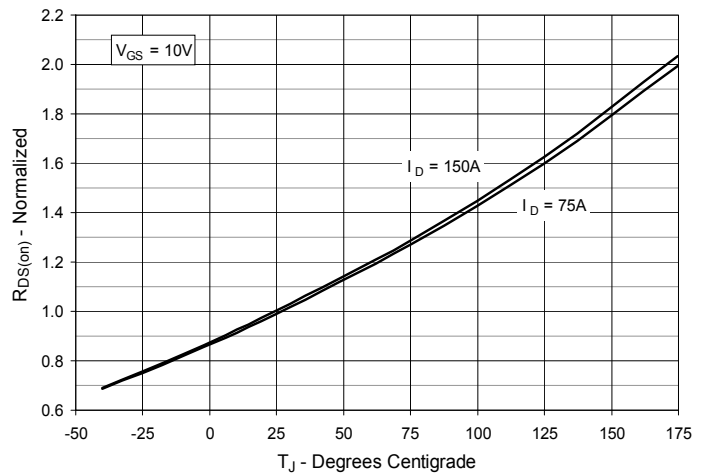


Fig. 5. $R_{DS(on)}$ Normalized to $I_D = 75\text{A}$ Value vs. Drain Current

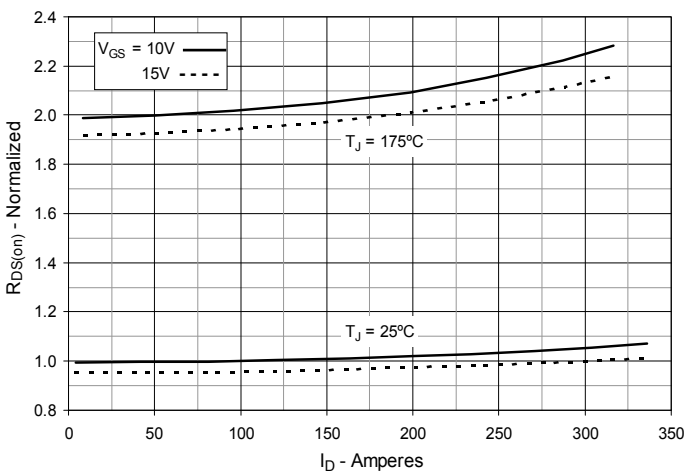


Fig. 6. Drain Current vs. Case Temperature

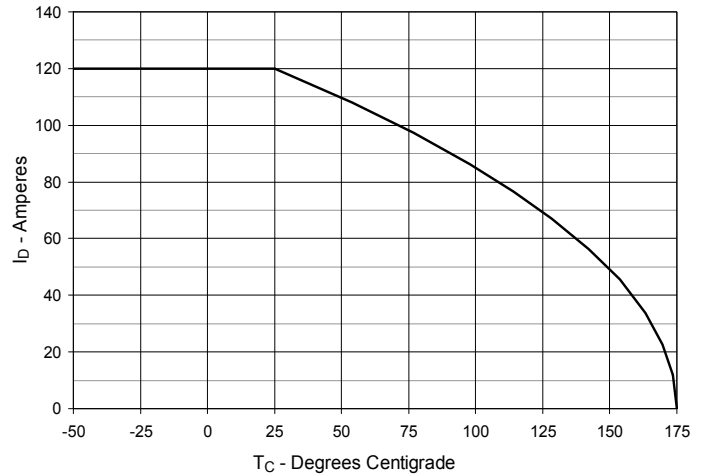


Fig. 7. Input Admittance

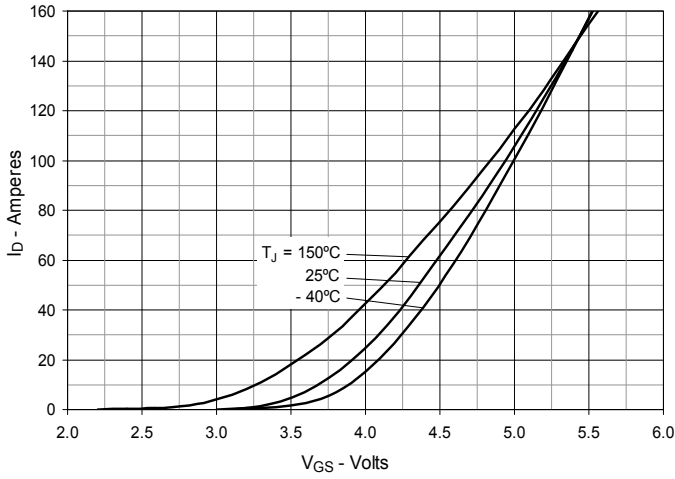


Fig. 8. Transconductance

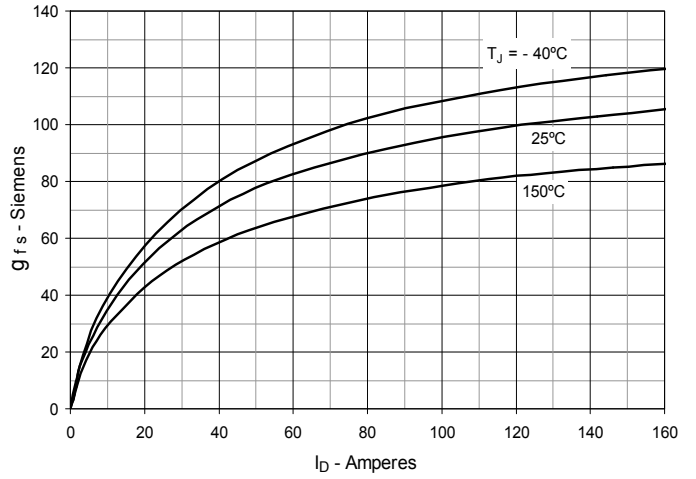


Fig. 9. Forward Voltage Drop of Intrinsic Diode

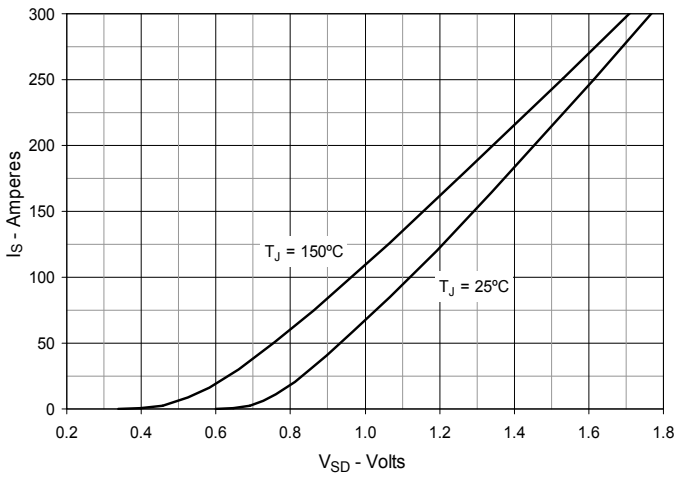


Fig. 10. Gate Charge

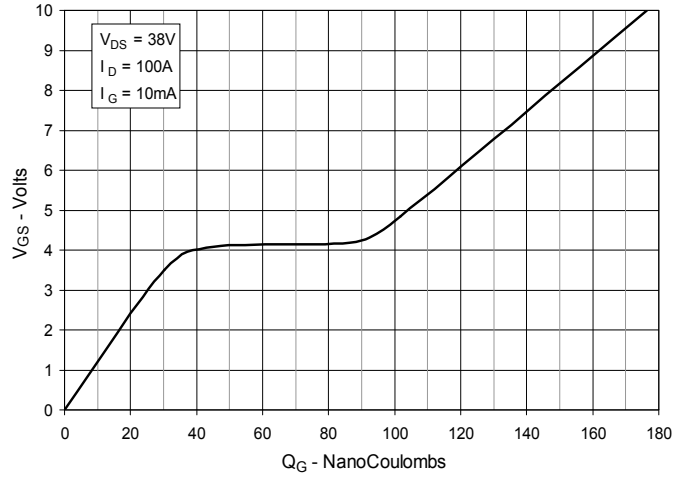


Fig. 11. Capacitance

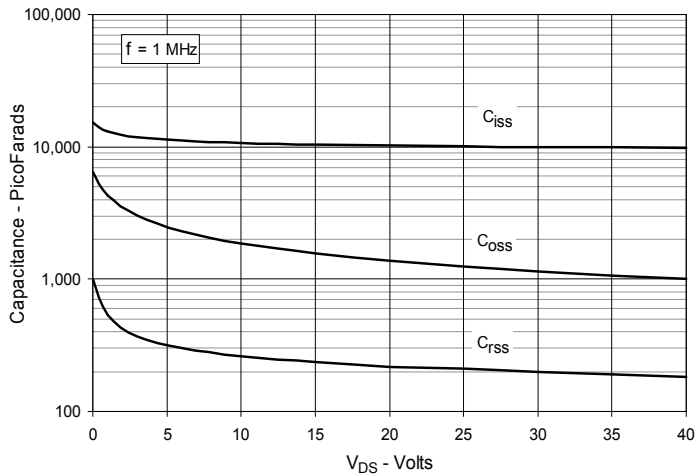
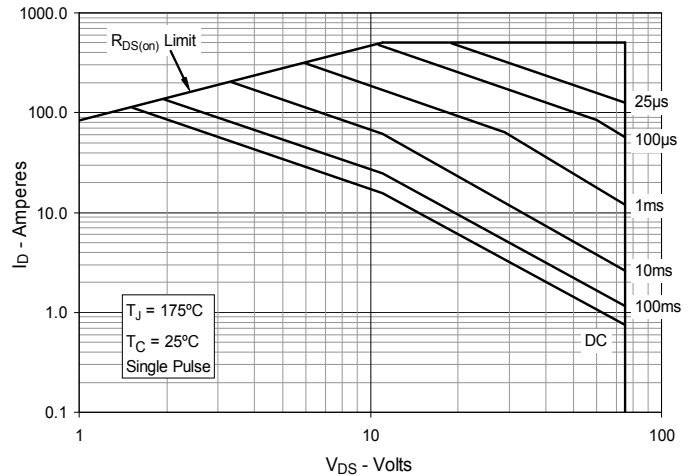


Fig. 12. Forward-Bias Safe Operating Area



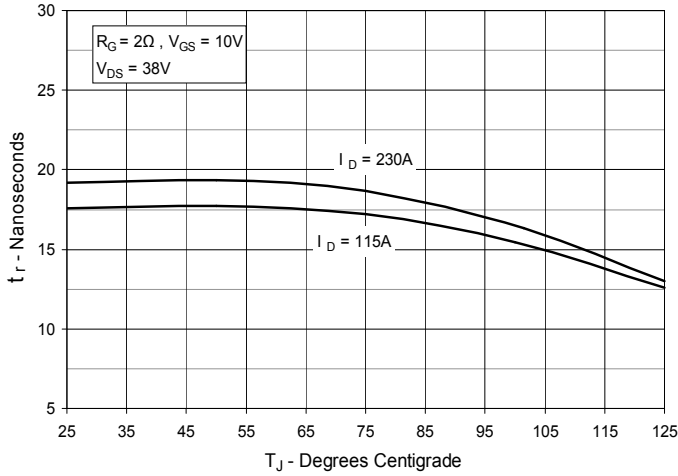
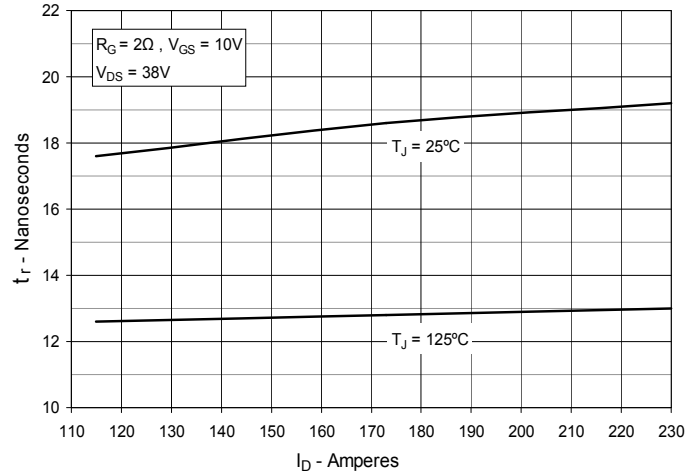
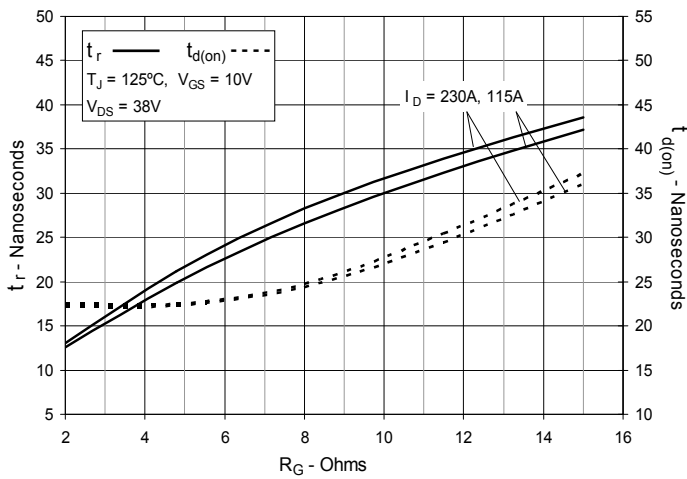
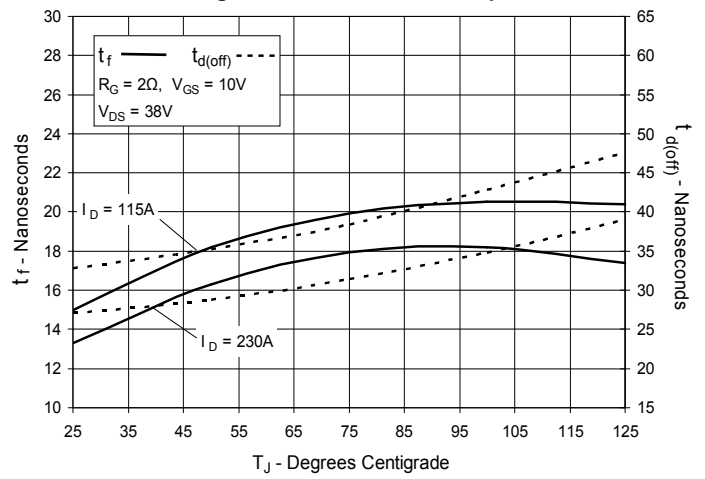
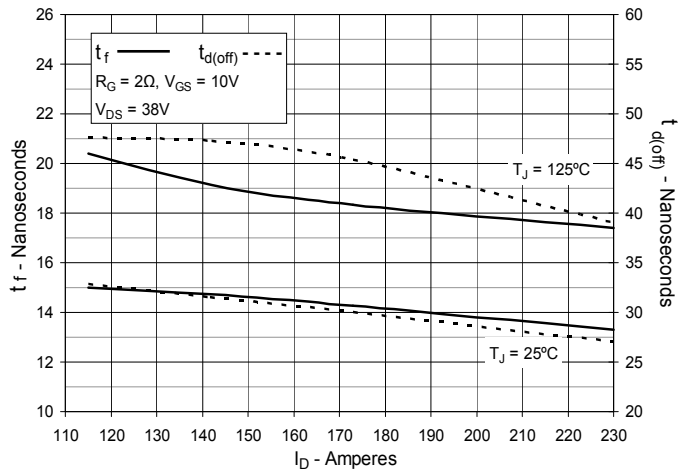
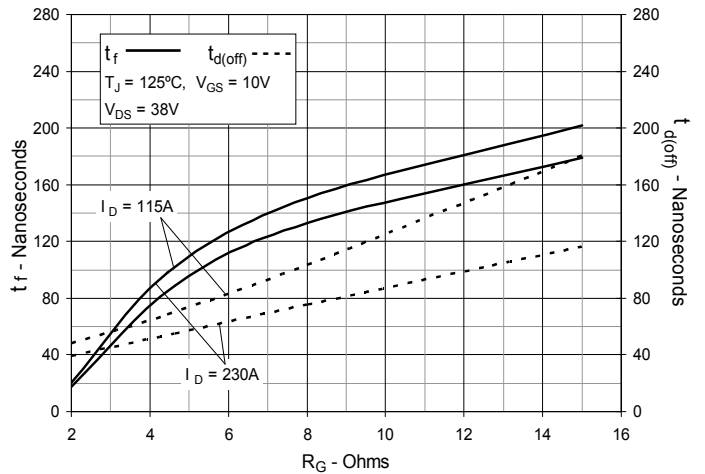
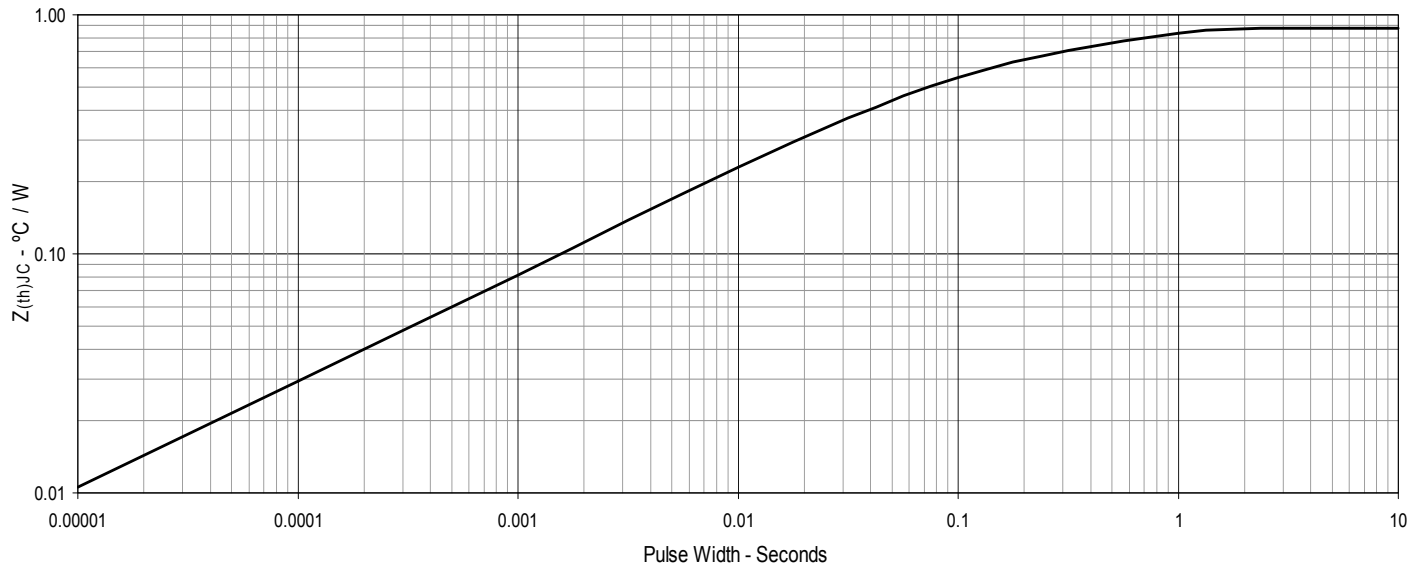
**Fig. 13. Resistive Turn-on
Rise Time vs. Junction Temperature**

**Fig. 14. Resistive Turn-on
Rise Time vs. Drain Current**

**Fig. 15. Resistive Turn-on
Switching Times vs. Gate Resistance**

**Fig. 16. Resistive Turn-off
Switching Times vs. Junction Temperature**

**Fig. 17. Resistive Turn-off
Switching Times vs. Drain Current**

**Fig. 18. Resistive Turn-off
Switching Times vs. Gate Resistance**


Fig. 19. Maximum Transient Thermal Impedance





Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.